SWITCHMODE™ Power Rectifier 60 V, 20 A

Features and Benefits

- Low Power Loss/High Efficiency
- High Surge Capacity
- 20 A Total (10 A Per Diode Leg)
- Guard-Ring for Stress Protection
- These are Pb-Free Devices

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube

MAXIMUM RATINGS

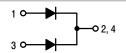
Please See the Table on the Following Page



ON Semiconductor®

http://onsemi.com

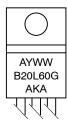
SCHOTTKY BARRIER RECTIFIER 20 AMPERES 60 VOLTS



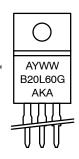


MARKING DIAGRAM

TO-220AB CASE 221A PLASTIC







A = Assembly Location

= Year

WW = Work Week
B20L60 = Device Code
G = Pb-Free Package
AKA = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBR20L60CTG	TO-220AB (Pb-Free)	50 Units / Rail
MBRF20L60CTG	TO-220FP (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
	I _{F(AV)}	10 20	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	240	А
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Storage Temperature	T _{stg}	- 65 to +175	°C
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

THERMAL CHARACTERISTICS

Maximum Thermal Resistance				°C/W
MBR20L60CT	Junction-to-Case	$R_{ hetaJC}$	2.3	
	Junction-to-Ambient	$R_{ hetaJA}$	70	
MBRF20L60CT	Junction-to-Case	$R_{ heta JC}$	5.2	
	Junction-to-Ambient	$R_{ heta JA}$	75	

ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_F=10~A,~T_C=25^\circ\text{C})\\ &(I_F=10~A,~T_C=125^\circ\text{C})\\ &(I_F=20~A,~T_C=25^\circ\text{C})\\ &(I_F=20~A,~T_C=125^\circ\text{C}) \end{aligned} $	VF	0.53 0.49 0.68 0.64	0.57 0.54 0.73 0.69	>
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$) (Rated DC Voltage, $T_C = 125^{\circ}C$)	i _R	118 52	380 96	μA mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

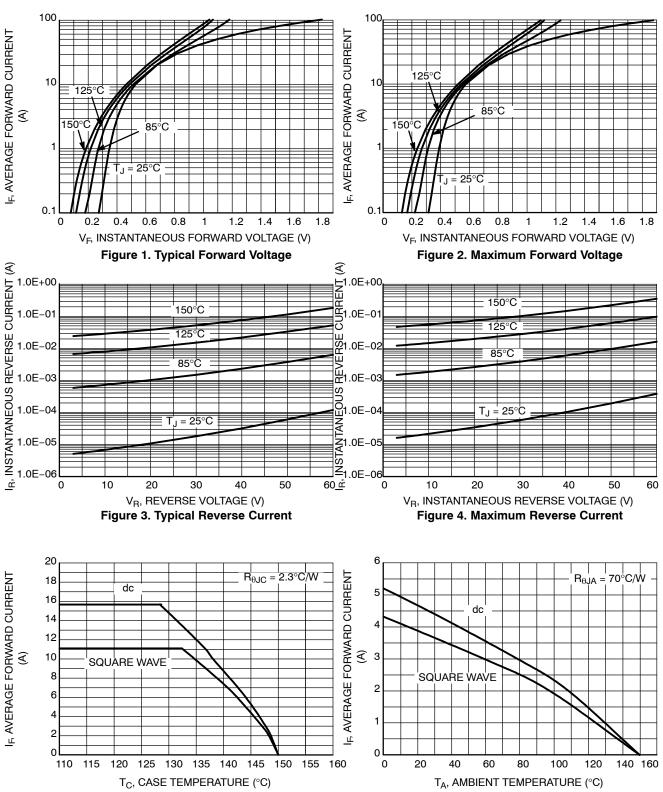


Figure 5. Current Derating, Case per Leg MBR20L60CT

Figure 6. Current Derating, Ambient per Leg MBR20L60CT

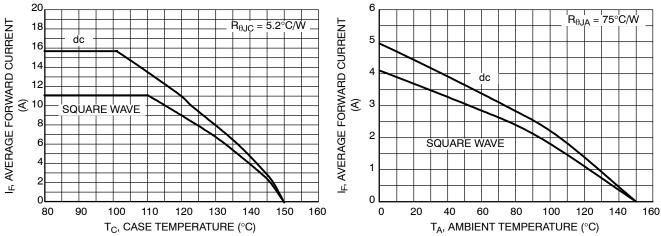


Figure 7. Current Derating, Case per Leg MBRF20L60CT

Figure 8. Current Derating, Ambient per Leg MBRF20L60CT

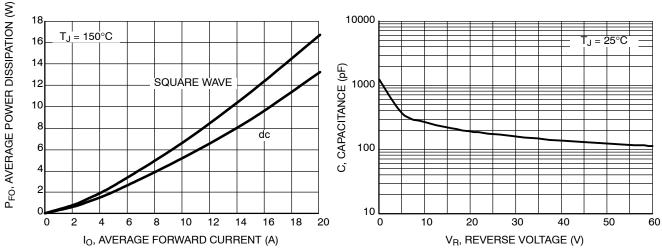


Figure 9. Forward Power Dissipation

Figure 10. Capacitance

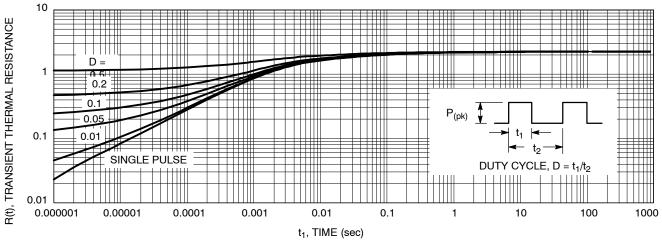


Figure 11. Thermal Response Junction-to-Case, per Leg for MBR20L60CT

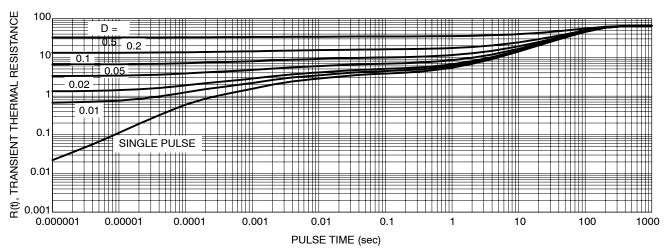


Figure 12. Thermal Response Junction-to-Ambient, per Leg for MBR20L60CT

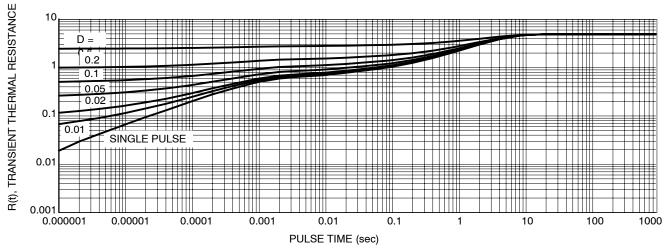


Figure 13. Thermal Response Junction-to-Case, per Leg for MBRF20L60CT

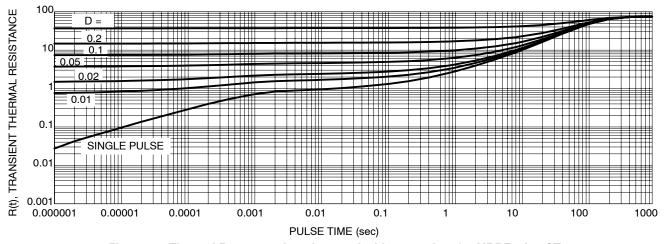
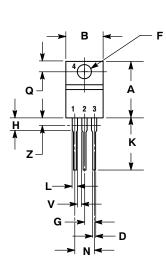
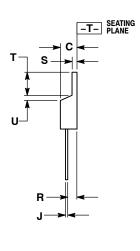


Figure 14. Thermal Response Junction-to-Ambient, per Leg for MBRF20L60CT

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AF**





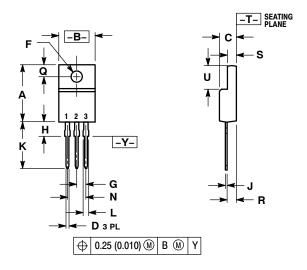
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

- STYLE 6:
 PIN 1. ANODE
 2. CATHODE
 3. ANODE
 4. CATHODE

PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03 **ISSUE J**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
С	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100	BSC	2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200	BSC	5.08	BSC
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

STYLE 3:

PIN 1. ANODE

CATHODE 3. ANODE

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